

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Built-in strain relief, ideal for automated placement
- Low forward voltage
- High forward surge current capability
- AEC-Q 101 qualified

Mechanical Data

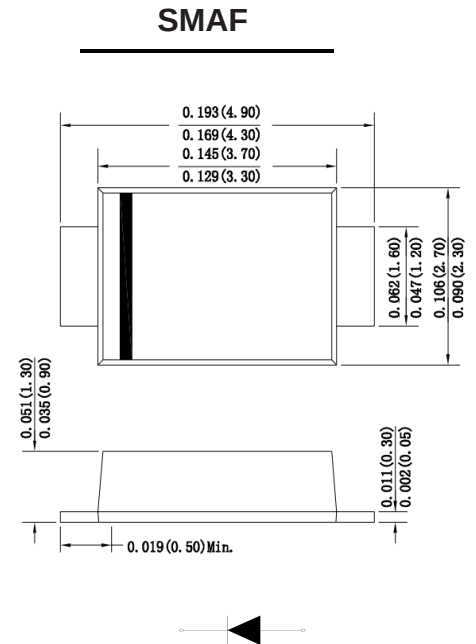
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0014 ounce, 0.038 grams



Dimensions in inches and (millimeters)

Maximum Ratings (Ta=25°C unless otherwise specified)

PARAMETER	SYMBOLS	VSSAF510HM3/H-CN	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	70	V
Maximum DC blocking voltage	V_{DC}	100	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	5.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	150.0	A
Typical thermal resistance	R_{qJA} R_{qJL}	65 20	$^\circ\text{C}/\text{W}$
Operating junction temperature range	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Note: Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas.

Electrical Characteristics (Ta=25°C unless otherwise specified)

PARAMETER	SYMBOLS	TYPE	MAX	UNITS
Maximum instantaneous forward voltage at 5.0A	V_F	0.56	0.60	V
Maximum DC reverse current at rated DC blocking voltage	I_R	10 2	200 50	μA mA

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

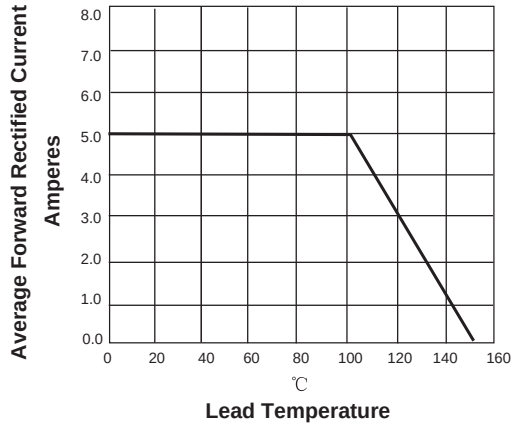


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

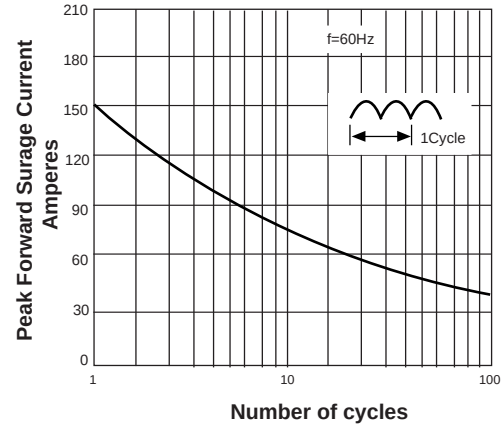


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

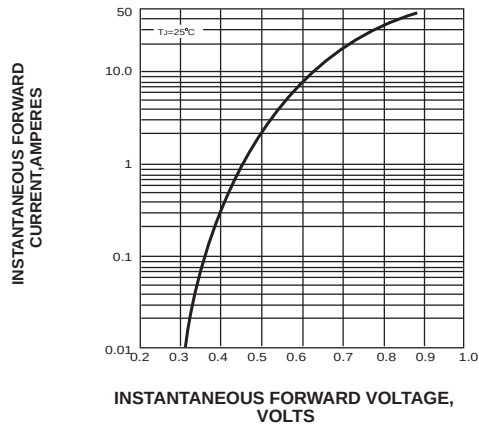
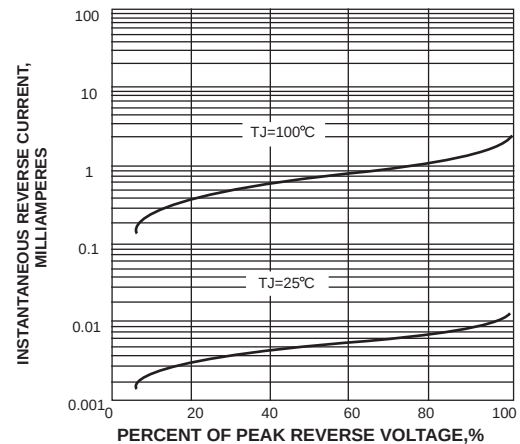
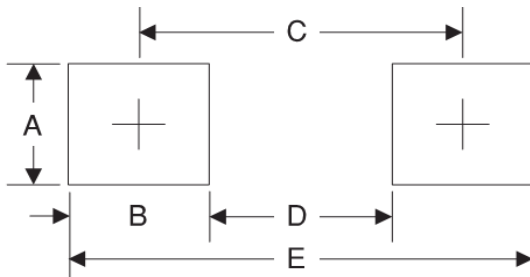


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

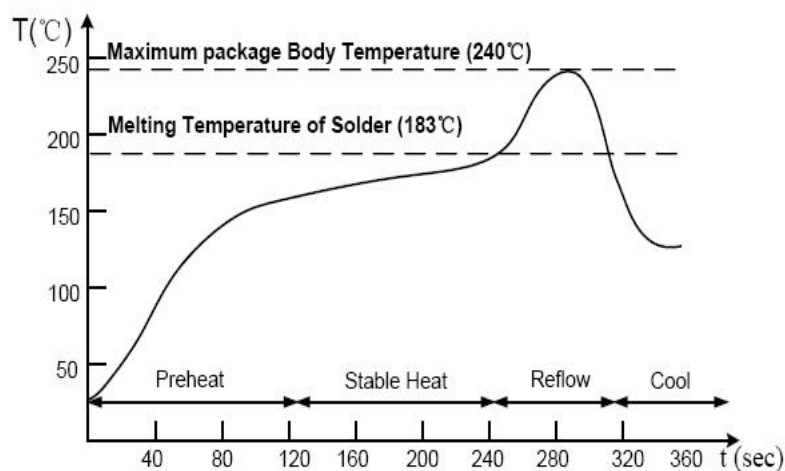


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.00	0.078
E	5.10	0.200

Suggested Soldering Temperature Profile

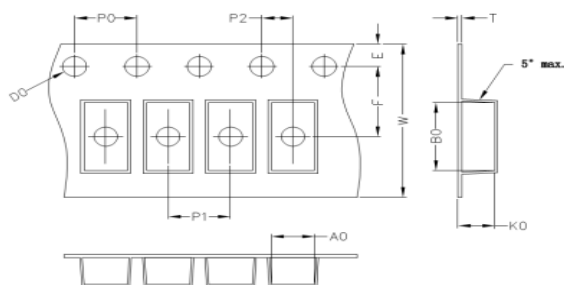


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
2.83	4.75	1.42	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	4.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMAF	7'	178	3	180	12	380*200*200	120

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